



Docket No.: Y0R919990172US4  
(20140-00298-US)  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Rajiv V. Joshi

Application No.: 10/052,451

Group Art Unit: 2822

Filed: January 18, 2002

Examiner: J. Brophy

For: SOFT METAL CONDUCTOR AND METHOD  
OF MAKING

AMENDMENT

**Box Non-Fee Amendment**  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated August 1, 2002 (Paper No. 6), please amend the above-identified U.S. patent application as follows:

In the Claims:

Please cancel claims 25, 40, 60 and 63-65 without prejudice to their reentry at a later date.

Please amend the claims as follows:

*Sub 67* 21. (Amended) A method of making a soft metal conductor for use in a semiconductor device which comprises depositing a first layer of said soft metal consisting of grains having grain sizes not less than 200 nm; and further comprising depositing a layer of said soft metal consisting of grains having a grain size of not more than 50 nm and a layer thickness of not less than 400 nm prior to said deposition process of said first layer of soft metal so as to provide a substantially scratch-free surface upon polishing in a subsequent CMP step.

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